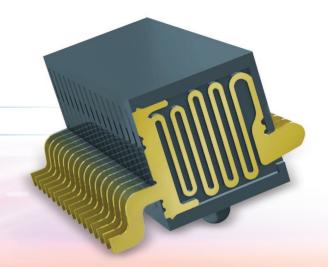
compliant connectors













electrical

high current high power high frequency low inductance

mechanical

low profile, high compliance
high to low force
high cycle life
shock and vibration
tolerant
flexibility

unique

Rohs/Reach Friendly options
sealed connectors for
harsh or sterile environments
miniature options for tight,
dense packaging
self-cleaning contacts
multiple 2D and 3D
tip options

uniquesolutions

for complicated applications

Each application demands specific connector attributes; i.e., material and chemical sensitive industries require sealed, self-cleaning connectors still capable of high-speed data transmission, while shock and vibration tolerant connectors are necessary for rugged environments. CCS offers electrical, mechanical, and specialized solutions to meet these demands.







application delivery

CCS's front end team
will learn your specific
application requirements.



solution concept

A tailor made solution will be developed from CCS's broad suite of intellectual property.



design analysis

CCS's engineers
can deliver a broad
spectrum of simulation
and characterization.



prototyping

can deliver usable prototypes for your initial qualifications.

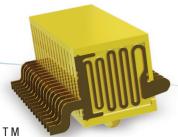


production

CCS's production department will meet your delivery schedule and produce all necessary quality documentation.







accordion™

Z-Height: Flexible - Designed to requirement

Compliance Travel: Excellent > .8mm
Inline Spacing: Excellent < .127mm

Array Spacing: OK - 1mm

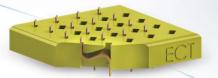
Tip Selection: 2D - Single or Multitip



peakportfolio

technology and talent

A connector is only as good as the sum of its parts; that's why CCS utilizes a unique portfolio of proprietary electro-mechanical contacts that evolved in the demanding test and measurement industry. Matching these elevated interconnect technologies with specifically designed integrated solutions allows CCS to deliver reliable, versatile, and robust connectors.



sliver

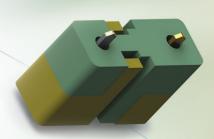
Z-Height: Excellent < 1.0mm

Compliance Travel: Excellent > .25mm

Inline Spacing: Excellent > .5mm

Array Spacing: Good > .65mm

Tip Selection: 2D - Single or Multitip



ZIP

Z-Height: Good > 2.0mm

Compliance Travel: Excellent > .8mm

Inline Spacing: Excellent > .3mm

Array Spacing: Excellent > .3mm

Tip Selection: 2D - Single or Multitip

Pogo

Z-Height: OK > 5.0mm

Compliance Travel: Excellent >.8mm
Inline Spacing: OK - .5mm

Array Spacing: OK > .5mm

Tip Selection: 3D - Multitip, Cup, or Spherical

accordion™

simple flexibility with reliability

Design

Simple and elegant single piece construction; designed per customer specifications.

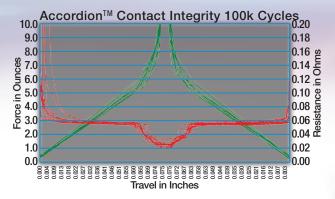
Application Highlights

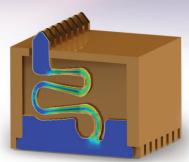
The accordion™ is ideal in harsh environments; utilizing a single contact eliminates the threat of liquid and debris build up between parts while also being tolerant of vibration and shock.

Features & Benefits

- Flat, single contact
 - Allows for tight pitch spacing
 - Stable electrical performance
 - Allows for tight pitch spacing; down to
 .127mm inline and 1mm array
- Flexible Z-Height, designed to requirement
- Can achieve .8mm compliance
- Low Cost, perfect for low to mid volume applications
- Patented scrub action
- Removes oxides from contacts and mates
- Wipes foreign debris
- Overcomes failure from plating breakdown

- · Detailed tip geometries
 - Pointed
 - 2D cupped
 - Radius
- Infinite configurations
- Advantages over common single beam designs
 - Superior manufacturing process allows for greater accuracy and feature repeatability
- Distribution of material stress allows contacts that last much longer than competitive designs







option available; page 12

sliver

low profile, high value

Design

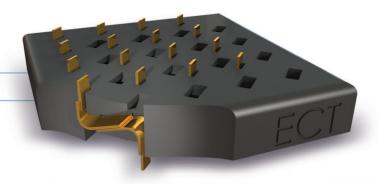
Innovative dual contact construction; designed per customer specifications

Application Highlights

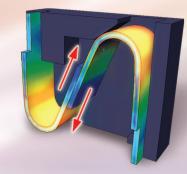
Efficient use of Z axis makes the Sliver ideal for low profile and difficult packaging applications

Features & Benefits

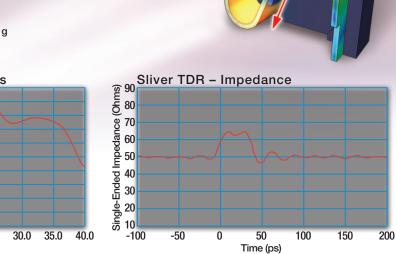
- Patented low profile, high compliance contact
 - Low cost, ideal for high volume applications
 - Can achieve compliance equaling 50% of its overall length
 - Less than 1.0mm compressed height
 - Superior conductive path with low inductance
 - Allows for tight pitch spacing; down to .5mm inline and .65mm array
- Single piece molded housing
 - Lowers tooling costs



- Patented sliding action
 - Provides maximum compliance while maintaining the lowest Z-Height package in the industry
- Mitigates internal stresses









high performance and value

Design

Patented flat technology with external spring construction. Custom and standard product options available

Application Highlights

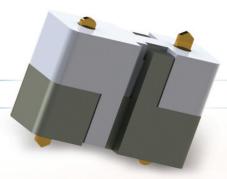
With .15mm to .8mm solutions, ZIP is great for high density, low profile interposers.

Features & Benefits

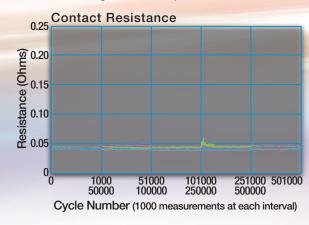
- Patented ZIP flat architecture contact
 - Proven reliability in the challenging semiconductor test industry
 - Designs exceeding 40GHz
 - Low Inductance
 - Compressed heights from 1.59mm to 7mm
 - Custom lengths available
 - Allows for tight pitch spacing; down to .3mm inline and array
- · Patented scrub action
- Removes oxides from contacts and mates
- Wipes foreign debris
- Overcomes failure from plating breakdown
- · Off the shelf capability
 - Short run and high volume manufacturing



option available; page 12



Detailed tip geometries
 2D; single or multitip





pogo

versatility and variety

Design

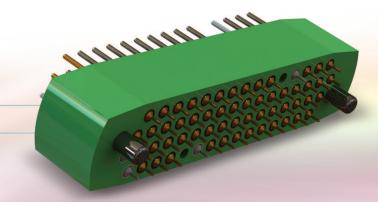
Proven multi-piece radial construction. Custom and standard product options available

Application Highlights

Mature design portfolio fits countless applications and provides outstanding performance.

Features & Benefits

- Spring probe contact (many patented designs)
 - Generous travel, can achieve .8mm compliance
 - Down to .5mm pitch inline and array spacing
 - High to low force
 - High cycle life
 - High current
 - High reliability
 - Designed for rapid and repeated cycling
 - Compressed height down to 5mm
 - Deliberate biasing



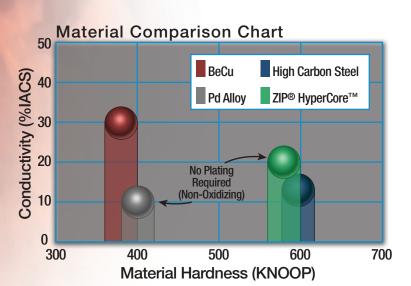
- 3D tip options
- Multitip
- Cup
- Spherical
- Mechanically superior to conductive elastomers



[base material] ultra durable and conductive

Born from the demanding high volume semiconductor testing world,
HyperCore is a proprietary base material developed for CCS's ZIP,
Accordion™ and Sliver connectors. HyperCore™ Base Material
requires no plating and features high hardness of 600 Knoop. It
resists tip deformation and wear typically generated by high volume
insertions or cleaning cycles. As it is non-plated, it can be repeatedly
cycled or cleaned, providing unprecedented connector life. Contact
resistance and RF behavior is equal to gold-plated BeCu.
HyperCore™ also resists oxides similar to gold, yielding performance

HyperCore[™] also resists oxides similar to gold, yielding performance that will not waver even in the most stringent environments.



500k Cycles Against Steel



HyperCore™

- No deformation
- No cleaning wear
- · No solder adhesion



BeCu

- Enlarged flat spots
- Solder adhesion (even after cleaning)
- Gold and Nickel plating worn



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